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MDT0350AIH-MULTI	240 x 32	Multi Interface	TFT Module				
(MCT035W0E240320PMLIPS)		Specification					
Version: 1		Date: 18/05/2017	7				
	Revision						
1	18/05/2017	First issue					

Display F	eatures		
Display Size	3.5"		
Resolution	240 x 320		
Orientation	Portrait		
Appearance	RGB		1
Logic Voltage	2.8V		oHS ompliant
Interface	Multi	IVK	$(0 \mid T \mid S)$
Brightness	500 cd/m <sup>2</sup>	/ A 23	mpliant
Touchscreen	SPLA	1 00	mpnant
Module Size	63.00 x 85.00 x 3.00mm		
Operating Temperature	-30°C ~ +85°C		
Pinout	50 way FFC	Box Quantity	Weight / Display
Pitch	0.5mm		

\* - For full design functionality, please use this specification in conjunction with the HX8347A specification.(Provided Separately)

Display Accessories				
Part Number	Description			
MPBV5 Kit	Interconnect board that converts a 50-way FFC to 50 crimp-wire connector.			
MCIB-12	Uno32 Break-out Board with SD Card and LED Backlight Driver. The MCIB-12 Board can be used for any display with a 4 bit, 8 bit, I2C or SPI interface.			

Optional Variants					
Appearances	Voltage				

### \* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silico n TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 3.5'TFT-LCD contains 240x320 pixels, and can display up to 65K/262K colors.

#### \* Features

-Low Input Voltage: 3.3V(TYP)

-Display Colors of TFT LCD: 65K/262K colors

-Interface: 8/16/18Bit MCU Interface

3 SPI+16/18Bit RGB Interface

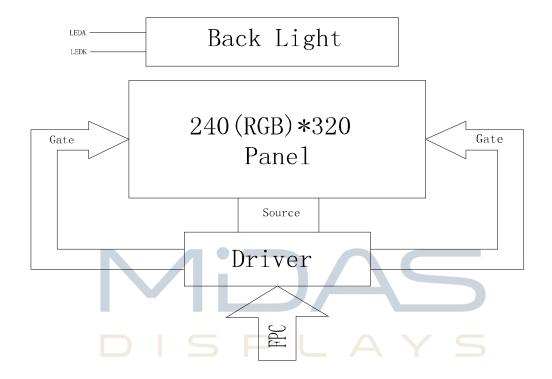
3 line Serial Interface

General Information	Specification	Unit	Note	
Items	Main Panel	Unit		
Display area(AA)	53.28(H)*71.04 (V) (3.5inch)	mm	-	
Driver element	TFT active matrix	-	-	
Display colors	65K/262K	colors	-	
Number of pixels	240(RGB)*320	dots	-	
Pixel arrangement	RGB vertical stripe	-	-	
Pixel pitch	0.222(H)*0.222(V)	mm	-	
Viewing angle	Free	o'clock	-	
Controller IC	MANUHX8347ATURE •	SUPPL	.Y -	
Display mode	Transmissive/ Normally Black	-	-	
Operating temperature	-30∼+85	$^{\circ}$ C	-	
Storage temperature	<b>-40∼+90</b>	$^{\circ}$	-	

#### \* Mechanical Information

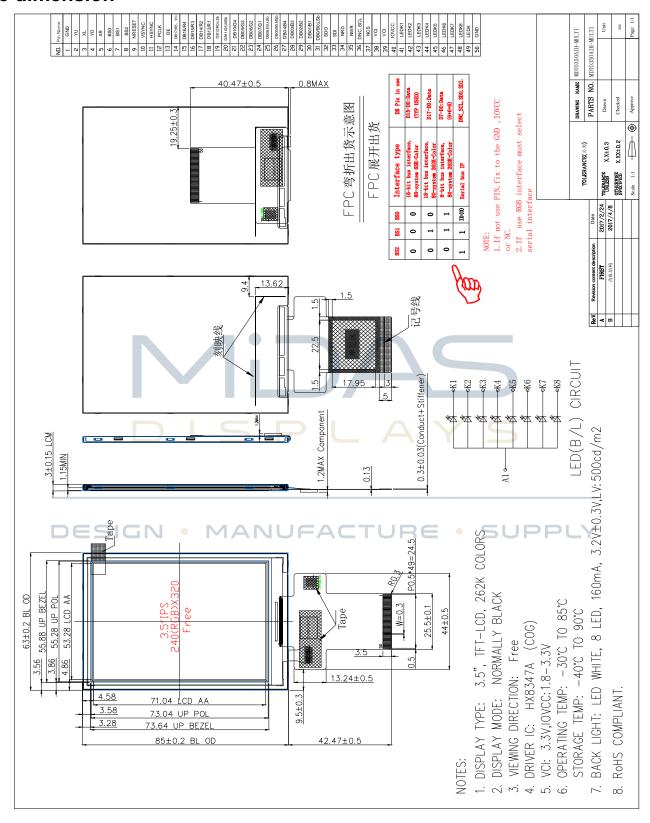
ltem		Min.	Тур.	Max.	Unit	Note
Module size	Horizontal(H)		61.08		mm	-
	Vertical(V)		84.09		mm	-
	Depth(D)		2.6		mm	-
Weight			TBD		g	-

# **Block Diagram**



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## **Outline dimension**



# **Input terminal Pin Assignment**

1 GND Ground. P 2 YU(NC) Touch panel Top Film Terminal A/D 3 XL(NC) Touch panel LIFT Glass Terminal A/D 4 YD(NC) Touch panel Bottom Film Terminal A/D 5 XR(NC) Touch panel Bottom Film Terminal A/D 6 BS0 MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface, Fix this pin at VCI and GND.  9 NRESET This signal will reset the device and must be applied to properly initialize the chip.  10 VSYNC Frame synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.  11 HSYNC Line synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.  12 PCLK Dot clock signal for RGB interface operation. fix this pin at VCI or GND when not in use.  13 DE Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  14-31 DB17-DB0 Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  15 Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  16 Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  17 DB17-DB0 Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  18 DB17-DB0 Serial data output pin in serial bus system interface. If not used, please open this pin.  2 SD0 Serial data output pin in serial bus system interface. If not used, fix this pin at VCI or GND.  33 SDI If not used, fix this pin at VCI or GND.  34 NRD Serves as a read signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use.  1 In the system of the serial interface. If not used, fix this pin at VCI or GND when not in use.  1 In the system of the serial interface. If not used, fix this pin at VCI or GND when not in use. If not used, fix this pin at VCI or GND when not in use. If not used, fix this pin at VCI or GND when not in use. If not used, fix this pin at VCI or GND when not in use. If not used, fix this pin at VCI or GND when not in	NO.	SYMBOL	DISCRIPTION	I/O
3 XL(NC) Touch panel LIFT Glass Terminal A/D 4 YD(NC) Touch panel Bottom Film Terminal A/D 5 XR(NC) Touch panel Right Glass Terminal A/D 6 BS0 MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface. Fix this pin at VCI and GND.  9 NRESET This signal will reset the device and must be applied to properly initialize the chip. Frame synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.  11 HSYNC Line synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.  12 PCLK Dot clock signal for RGB interface operation. fix this pin at VCI or GND when not in use.  13 DE Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  14-31 DB17-DB0 Tabel Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  14-31 DB17-DB0 Serial data output pin in serial bus system interface. I Fix to GND level when not in use  32 SD0 If not used, please open this pin.  Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at VCI or GND.  34 NRD Serves as a read signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use.  1 In NWR NWR pin, serves as a write signal I	1	GND	Ground.	Р
4 YD(NC) Touch panel Bottom Film Terminal A/D  5 XR(NC) Touch panel Right Glass Terminal A/D  6 BS0 MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface.  7 BS1 Interface must select serial interface.  8 BS2 Fix this pin at VCI and GND.  1 INRESET This signal will reset the device and must be applied to properly initialize the chip.  10 VSYNC Frame synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.  11 HSYNC Line synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.  12 PCLK Dot clock signal for RGB interface operation. fix this pin at VCI or GND when not in use.  13 DE Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  14-31 DB17-DB0 Interface mode. Fix to GND level when not in use.  15 Serial data output pin in serial bus system interface. If not used, please open this pin.  26 Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at VCI or GND.  37 SOI Serves as a read signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use. In the line of the signal of the signal input signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use. In the line of the signal of the sign	2	YU(NC)	Touch panel Top Film Terminal	A/D
State	3	XL(NC)	Touch panel LIFT Glass Terminal	A/D
BS0	4	YD(NC)	Touch panel Bottom Film Terminal	A/D
Interface must select serial interface.	5	XR(NC)	Touch panel Right Glass Terminal	A/D
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fix this pin at VCI or GND when not in use  12	10	VSYNC		I
Fix this pin at VCI or GND when not in use.  Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.  18-bit parallel bi-directional data bus for MCU system and RGB interface mode. Fix to GND level when not in use  Serial data output pin in serial bus system interface. If not used, please open this pin.  Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at VCI or GND.  NRD Serves as a read signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use.  NWR NWR pin, serves as a write signal  I  NWR pin, serves as a write signal	11	HSYNC		I
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36 DNC_SCL DNC_SCL pin as Serial Clock when operates in the serial interface	35	NWR	NWR pin, serves as a write signal	I
	36	DNC_SCL	DNC_SCL pin as Serial Clock when operates in the serial interface	I

37	NCS	Chip select input pin ("Low" enable). fix this pin at VCI or GND when not in use.	I
38	VCI	Supply voltage(3.3V).	Р
39	VCI	Supply voltage(3.3V).	Р
40	IOVCC	Supply voltage(1.8-3.3V)	Р
41	LEDK1	Cathode pin OF backlight	Р
42	LEDK2	Cathode pin OF backlight	Р
43	LEDK3	Cathode pin OF backlight	Р
44	LEDK4	Cathode pin OF backlight	Р
45	LEDK5	Cathode pin OF backlight	Р
46	LEDK6	Cathode pin OF backlight	Р
47	LEDK7	Cathode pin OF backlight	Р
48	LEDK8	Cathode pin OF backlight	Р
49	LEDA	Anode pin of backlight	Р
50	GND	Ground.	Р

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# **LCD Optical Characteristics**

# Optical specification

Item		Symbol	Condition	Min.	Тур.	Max.	Unit.	Note
Contrast R	atio	CR			800			
Response	Rising	T <sub>R</sub>			16	21		
time	Falling	T <sub>F</sub>			19	24	msec	
Color gam	nut	S(%)			72		%	
		W <sub>X</sub>		0.336	0.340	0.344		
	White	$W_Y$	Θ=0	0.356	0.360	0.364		
	Red	R <sub>X</sub>	Normal viewing angle	0.618	0.620	0.622		
Color Filter		$R_Y$		0.338	0.340	0.342		
Chromacicity	Green	G <sub>X</sub>		0.348	0.350	0.352		
		G <sub>Y</sub>		0.620	0.622	0.624		
		B <sub>X</sub>		0.148	0.150	0.152		
	Blue	B <sub>Y</sub>	1	0.033	0.035	0.037		
		ΘL			80			
	Hor.	ΘR			80			
Viewing angle	ESIGI	J Ou I	1ACR>10FA	CT <u>U</u> F	R = 80° ≤	5UPP	LY	
	Ver.	ΘD			80			
Option View D	irection			Free				

# **Measuring Condition**

■ Measuring surrounding: dark room

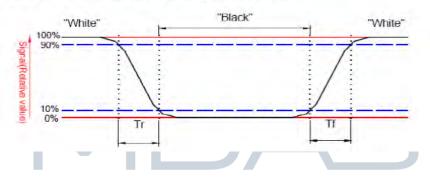
■ Ambient temperature: 25±2°C

■ 15min. warm-up time.

## **Measuring Equipment**

- Note 1: Ambient temperature = 25°C.
- Note 2: To be measured with a viewing cone of 2°by Topcon luminance meter BM-5A.
- Note 3: To be measured with Otsuta chromaticity meter LCF-2100M, CF only measure under C light simulation
- Note 4: CTC shipping status is cell without polarizer. Transmittance of Specification is cell with polarizer. The tolerance of Transmittance is  $\pm 10\%$ .
- Note 5: Definition of response time:

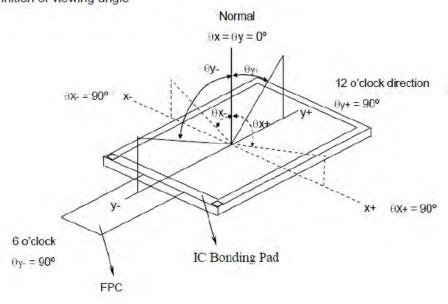
The output signals of TRD-100 are measured when the input signals are changed to "White" (falling time) and from "White" to "Black" (rising time), respectively. The interval is between the 10% and 90% of amplitudes. Refer to figure as below.



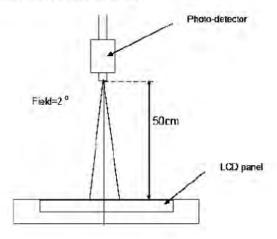
Note 6: Definition of contrast ratio:

Contrast ratio is calculated by the following formula.

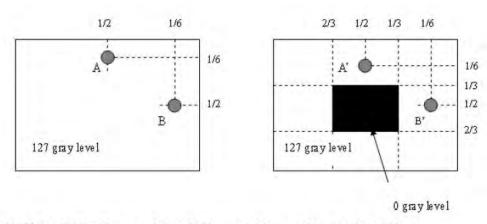
Note 7: Definition of viewing angle



Note 8: Optical characteristic measurement setup.



Note 9:



I LA-LA' I / LA x 100%= 2% max., LA and LA' are brightness at location A and A'. I LB-LB' I / LB x 100%= 2% max., LB and LB' are brightness at location B and B'.

#### **Electrical Characteristics**

**Absolute Maximum Rating (Ta=25 VSS=0V)** 

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VCI	-0.3	4.2	V
Digital interface supple Voltage	IOVCC	-0.3	3.3	V
Operating temperature	T <sub>OP</sub>	-30	+85	${\mathbb C}$
Storage temperature	T <sub>ST</sub>	-40	+90	$^{\circ}$

#### NOTE:

If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

#### **DC Electrical Characteristics**

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	MVCIN I			• 3.3JP	PWY	
Digital interface supple Voltage	IOVCC	1.65	1.8	3.3	V	
Normal mode Current consumption	IDD		9		mA	
Lovel imput veltage	V <sub>IH</sub>	0.7IOVCC		IOVCC	V	
Level input voltage	V <sub>IL</sub>	GND		0.3IOVCC	V	
Lovel output valtage	V <sub>OH</sub>	0.8IOVCC		IOVCC	V	
Level output voltage	V <sub>OL</sub>	GND		0.2IOVCC	V	

### **LED Backlight Characteristics**

The back-light system is edge-lighting type with 8chips White LED

Item	Symbol	Min.	Тур.	Max.	Unit	Note
Forward Current	I <sub>F</sub>	120	160		mA	
Forward Voltage	$V_{F}$		3.2		V	
LCM Luminance	L <sub>V</sub>		450		cd/m2	Note3
LED life time	Hr	50000			Hour	Note1,2
Uniformity	AVg	80			%	Note3

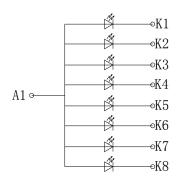
### Note (1):

LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

Ta=25±3 ℃, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25℃ and IL=160mA. The LED lifetime could be decreased if operating IL is larger than 160mA. The constant current driving method is suggested.

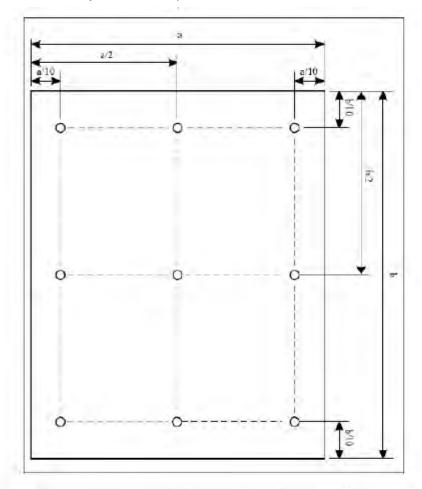
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LED(B/L) CIRCUIT

LED WHITE, 8 LED, 160mA, 3.2V±0.3V

NOTE 3: Luminance Uniformity of these 9 points is defined as below:

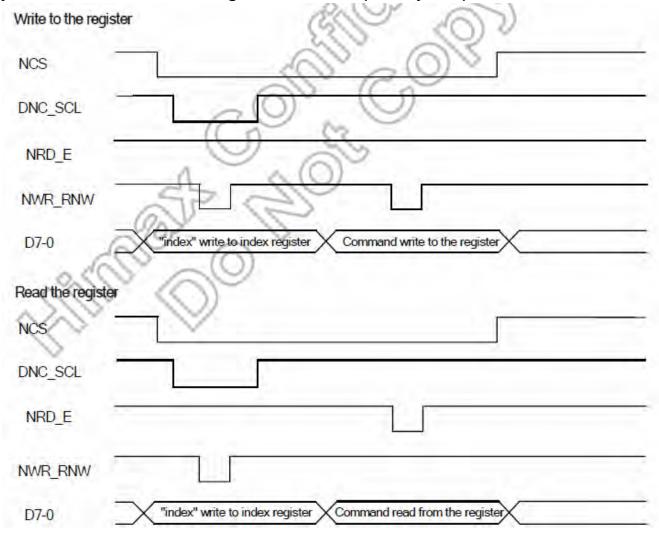


Uniformity =  $\frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$ 

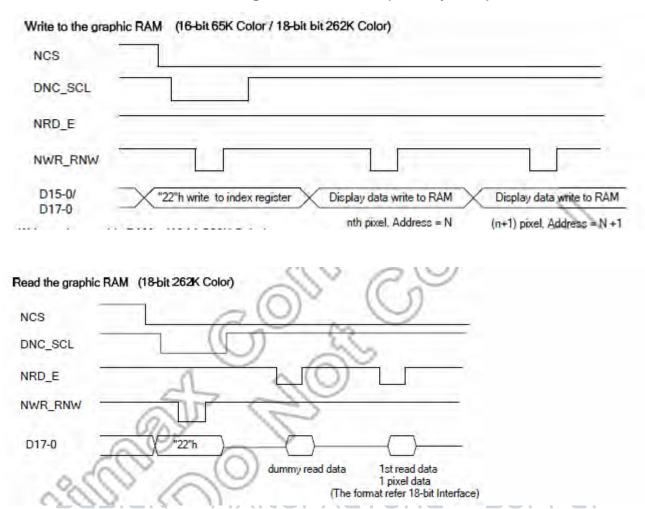
$$Luminance = \frac{Total \ Luminance \ of \ 9 \ points}{9}$$

## **AC Characteristic**

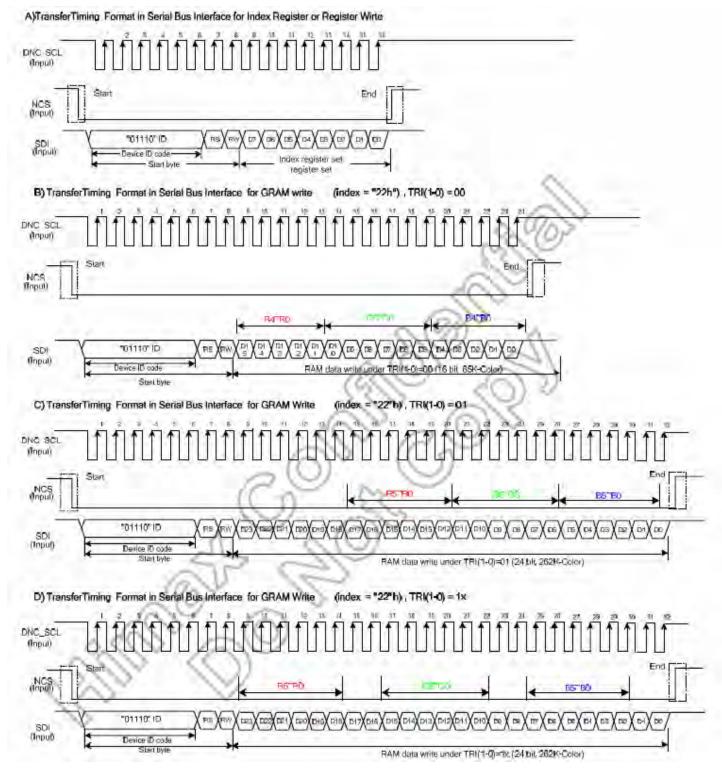
## Display Parallel 8-bit Interface Timing Characteristics (8080 system)

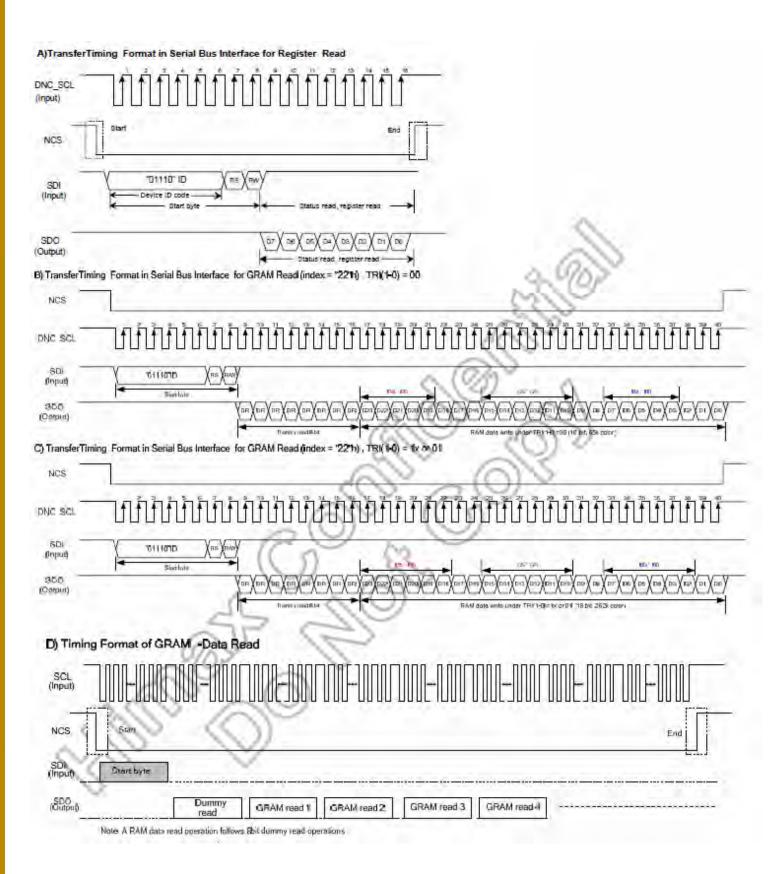


## **Display Parallel 16/18-bit Interface Timing Characteristics (8080 system)**

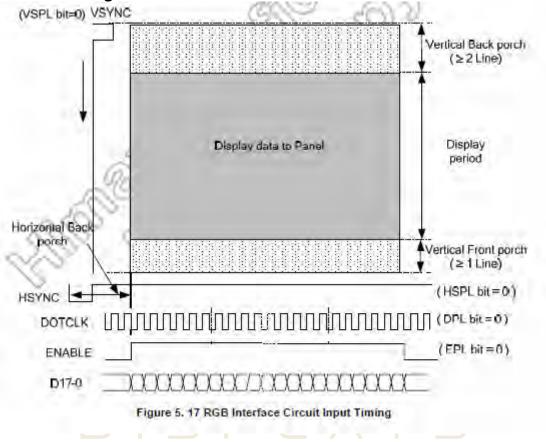


### **Display Serial Interface Timing Characteristics (3-line SPI system)**





### **Parallel RGB Interface Timing Characteristics**



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## 16 bit/pixel color order (R 5-bit, G 6-bit, B 5-bit), 65,536 colors (CSEL(2-0) = "101")

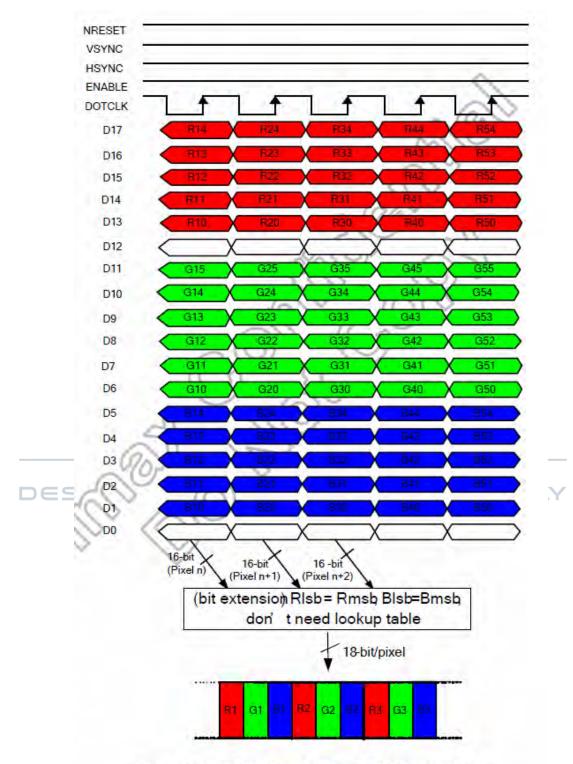
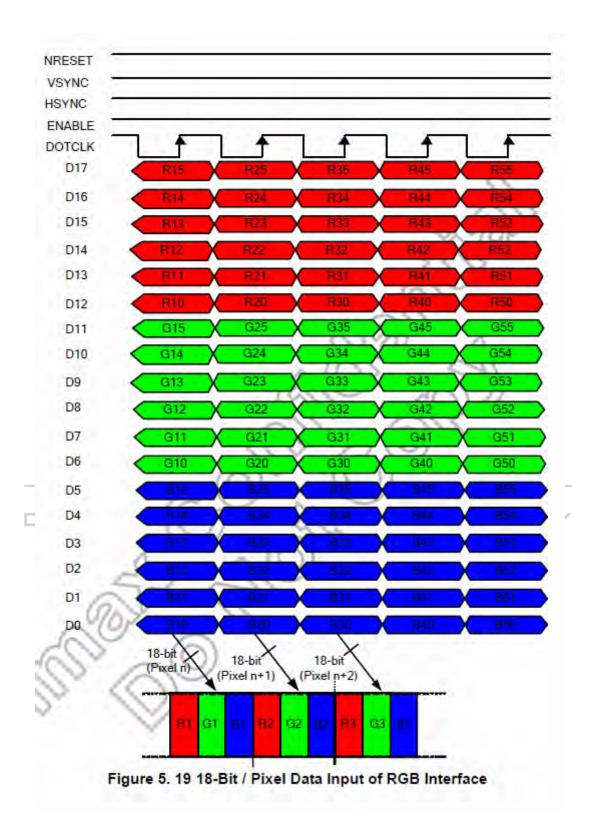


Figure 5. 18 16-Bit / Pixel Data Input of RGB Interface

## 18 bit/pixel color order (R 6-bit, G 6-bit, B 6-bit), 262,144 colors (CSEL(2-0) = "110")



## **LCD Module Out-Going Quality Level**

#### **VISUAL & FUNCTION INSPECTION STANDARD**

#### **Inspection conditions**

Inspection performed under the following conditions is recommended.

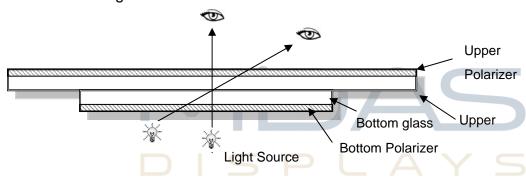
Temperature : 25±5°C

Humidity: 65%±10%RH

Viewing Angle: Normal viewing Angle.

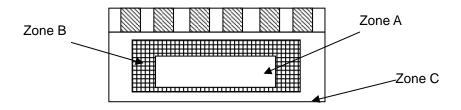
Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



#### **Definition**

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Zone A: Effective Viewing Area(Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A+Zone B) which can not be seen after assembly by customer.)

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer.

# Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class  $\,$  II AQL:

Major defect	Minor defect		
0.65	1.5		

LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be	Items to be Criteria	
	inspected		defects
		1) No display, Open or miss line	
1	Functional defects	2) Display abnormally, Short	
'	Functional defects	3) Backlight no lighting, abnormal lighting.	
		4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing	
3	Outline dimension	is not allowed	
4	Color tone	Color unevenness, refer to limited sample	
_	Soldering	Good soldering , Peeling off is not allowed.	Minor
5	appearance	MANUSACTURE : E	Minor
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	OFFCY

# Criteria (Visual)

Number	Items	Criteria(mm)				
1.0 LCD Crack/Broken	(1) The edge of LCD broken					
NOTE:		X Y Z				
X: Length Y: Width		≤3.0mm				
Z: Height L: Length of ITO, T: Height of LCD	(2)LCD corner broken	X Y Z  ≤3.0mm ≤L ≤T				
DE	(3) LCD crack	Crack Not allowed				

Number	Items	Criteria (mm)						
2.0	Spot defect	① light dot (LCD/TP/Polarizer black/white spot , light dot, pinhole, dent,						
	<u> </u>	stain)						
		Zone	Acc	cep able Q	ty			
		Size (mm)	Α	В	С			
		Ф≤0.30	Ignore					
		0.20<Φ≤0.3	3( distance ≥ 10mm)		lanor			
	X	0.25<Φ≤0.35	2		Ignor			
	φ (V. V) (0	Ф>0.4	0					
	Ф=(X+Y)/2	②Dim spot (LCD	/TP/Polarizer dir	n dot, light l	eakage、dark	spot)		
		Zone	Ac	ceptable Qt	у			
		Size (mm)	А	В	С			
		Ф≤0.3	Ignor	е				
		0.2<Φ≤0.3	3( distance ≥ 10mm)					
		0.25<Φ≤0.35	2		Ignore			
		Ф > 0.4			5			
		③ Polarizer accidented spot						
		Zone	A	cceptable Q	ty			
	DESIG	Size (mm)	А	В	С			
		Ф≤0.3 № 0	JFAC Ignore •		SUPPL	.Y		
		0.25<Φ≤0.5	2( distance ≥ 10mm)		Ignore			
		Ф>0.5	0					
	Line defect					_		
	(LCD/TP	Width(mm)	Longth/mm	Accep	table Qty			
	/Polarizer	Width(mm)	Length(mm	А	ВС			
	black/white line, scratch, stain)	Ф≤0.05	Igno e	Igno e Ignore				
		0.04 <w≤0.07< td=""><td>L≤3.0</td><td>N≤2</td><td>Ignore</td><td></td></w≤0.07<>	L≤3.0	N≤2	Ignore			
		0.06 <w≤0.09< td=""><td>L≤2.0</td><td>N≤2</td><td></td><td></td></w≤0.09<>	L≤2.0	N≤2				
		0.09 <w< td=""><td>Defi</td><td>ne as spot de</td><td>efect</td><td></td></w<>	Defi	ne as spot de	efect			
		1	1			J		

		Zone		Acceptable Qty				
	Polarizer	Size (mm)		Α	В	С		
3.0	Bubble	Ф≤0.2		Ignore				
		0.2<Φ≤0.4	4		e≧10 m)	lanoro		
		0.4<Φ≤0.6	6		2	Ignore		
		0.6<Ф		(	)			
4.0	SMT	According to IPC-part are major defe					n defect ar	nd missing
				1				1
			Size Φ(mm)	Ac	Acceptable Qty			
					Α	В	С	
		TP bubble/		Ф≤0.3	<u>Igno</u>			
		accidented		25<Φ≤0.3	3 (dista		Ignore	
		spot	0.2	25<Φ≤0.35	2			
				0.4<Ф	0			
		Assembly deflection		•	nd the edge	•	≤0.15mm	_

5.0	TP					
	Related					
						1規律性
			Newton Rin	ng area>1/	3 TP area	
		Newton				
		Ring	Newton Rin	ng area≤1/	3 TP area	<i>训(</i> )((l)
						2.排規書生
						11/1
						((((
						1))/
				<b>)</b> /_	7	似牛顿环
		TP corner	X	Y	Z	V.
		broken	P	L A	Z <lcd< td=""><td>X</td></lcd<>	X
		X: length	X≤3.0mm	Y≤3.0mm	thicknes	Z
_		Y: width	*			
	DESIGN	Z : height	Circuitry b	roken is no	t allowed.	SUPPLY
		TP edge	X	Y	Z	y X
		broken			Z <lcd< td=""><td>Z</td></lcd<>	Z
		X: length Y: width	X≤6.0mm	Y≤2.0mm	thicknes	6
		Z : height	* Circuitry b	oroken is no	ot allowed.	*
			23diti y t			

## Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

# **Reliability Test Result**

## Condition

ltem	Condition	Sample Size	Test Result	Note
Low Temperature Operating Life test	-30°C, 96HR	3ea	pass	-
Thermal Humidity Operating Life test	850℃90%RH, 96HR	3ea	pass	-
Temperature Cycle ON/OFF test	-30°C ↔ 85°C, ON/OFF, 20CYC	3ea	pass	(1)
High Temperature Storage test	90℃, 96HR	3ea	pass	-
Low Temperature Storage test	-40°C, 96HR	3ea	pass	-
ESD test	150pF, 330Ω, ±6KV(Contact)/± 8KV(Air), 5 points/panel, 10 times/point	5 L3ea P	pass	
Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: TSTL for 30 minutes -> normal temperature for 5 minutes -> TSTH for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours	3ea	pass	
Box Drop Test	1 Corner 3 Edges 6 faces, 66cm (MEDIUM BOX)	1box	pass	-

Note (1) ON Time over 10 seconds, OFF Time under 10 seconds

## **Cautions and Handling Precautions**

### **Handling and Operating the Module**

- (1) When the module is assembled, it should be attached to the system firmly.
- Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.
- If you have the droplets for a long time, staining and discoloration may occur.
- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
- Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

#### Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
- It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
- In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.